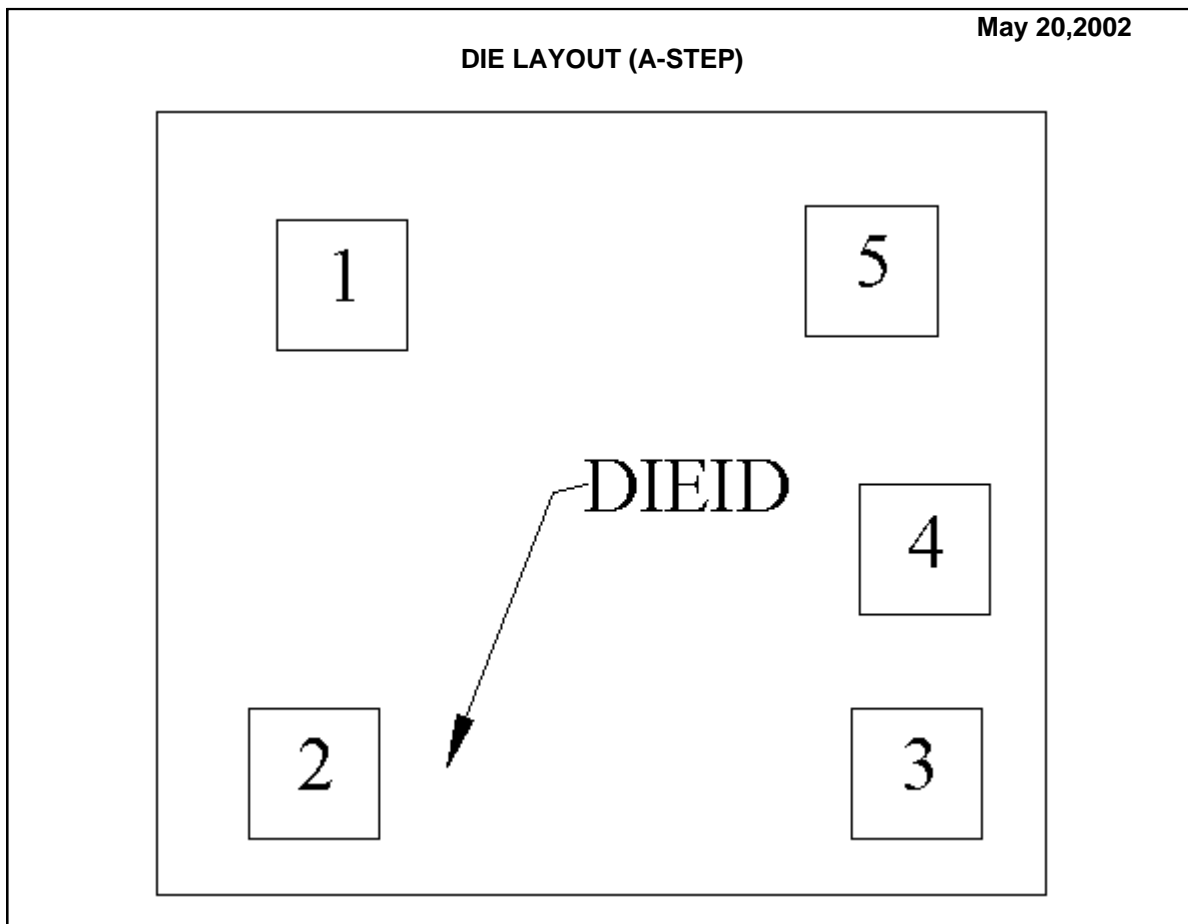


**LM397 MDC MWC
SINGLE GENERAL PURPOSE VOLTAGE COMPARATOR**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM397A	Bond Pad Opening Size (min)	127µm x 127µm
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	864µm x 762µm 34mils x 30mils	Back Side Connection	GND
Thickness	254µm Nominal		
Min Pitch	217µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL	PAD#	X/Y CORRINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
VIN -	1	-253	212	127	x	127
VS	2	-280	-262	127	x	127
OUTPUT	3	306	-262	127	x	127
GND	4	314	-45	127	x	127
VIN +	5	262	226	128	x	127

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